

N-Channel Super Junction Power MOSFET ~ III ~

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

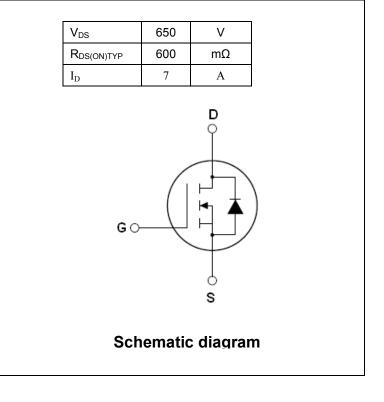
- •New technology for high voltage device
- •Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

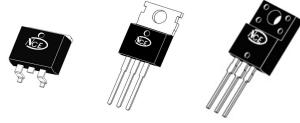
Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

Package Marking And Ordering Information						
Device	Device Package	Marking				
NCE65T680D	TO-263	NCE65T680D				
NCE65T680	TO-220	NCE65T680				
NCE65T680F	TO-220F	NCE65T680F				

Table 1. Absolute Maximum Ratings (T_c=25℃)





TO-263

TO-220

TO-220F

Parameter	Symbol	NCE65T680D NCE65T680	NCE65T680F	Unit
Drain-Source Voltage (VGs=0V)	Vds	65	50	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30		V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	7	7*	А
Continuous Drain Current at Tc=100°C	D (DC)	4.5	4.5*	А
Pulsed drain current (Note 1)	DM (pluse)	28	28*	А
Maximum Power Dissipation(Tc=25°C)	P _D	60	31.4	W
Derate above 25°C		0.48	0.25	W/°C
Single pulse avalanche energy (Note 2)	Eas	101		mJ
Avalanche current ^(Note 1)	I _{AR}	1.5		А
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	0.	28	mJ



NCE65T680D,NCE65T680,NCE65T680F

Parameter	Symbol	NCE65T680D NCE65T680	NCE65T680F	Unit
Drain Source voltage slope, $V_{DS} \leq 480 V$,	dv/dt	50		V/ns
Reverse diode dv/dt, $V_{DS} \leqslant 480 V, I_{SD} < I_D$	dv/dt	1	5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55	+150	°C

* limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE65T680D NCE65T680	NCE65T680F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	2.08	3.98	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25 $^{\circ}$ Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Мах	Unit	
On/off states							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	650			V	
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA	
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3		4	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3.5A		600	680	mΩ	
Dynamic Characteristics							
Input Capacitance	Clss			435		pF	
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		28		pF	
Reverse Transfer Capacitance	C _{rss}			3.3		pF	
Total Gate Charge	Qg	V =400V/L =7A		11		nC	
Gate-Source Charge	Q _{gs}	- V _{DS} =480V,I _D =7A, V _{GS} =10V		3.5		nC	
Gate-Drain Charge	Q _{gd}	VGS-10V		5		nC	
Switching times							
Turn-on Delay Time	t _{d(on)}			8		nS	
Turn-on Rise Time	tr	V _{DD} =380V,I _D =3.5A,		7		nS	
Turn-Off Delay Time	t _{d(off)}	R _G =4.7Ω,V _{GS} =10V		58	75	nS	
Turn-Off Fall Time	t _f			9	15	nS	
Source- Drain Diode Characteristics	·						
Source-drain current(Body Diode)	I _{SD}	T -25°0			7	А	
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			28	А	
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =7A,V _{GS} =0V		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			210		nS	
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I _F =3.5A,di/dt=100A/µs		0.85		uC	
Peak Reverse Recovery Current	I _{rrm}			8		А	

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25\Omega



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

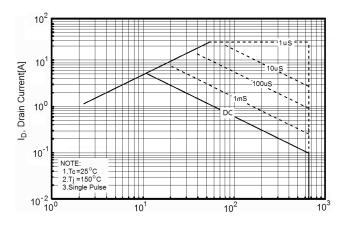


Figure3. Source-Drain Diode Forward Voltage

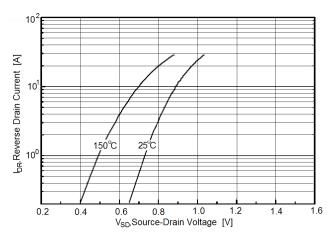


Figure 5. Transfer characteristics

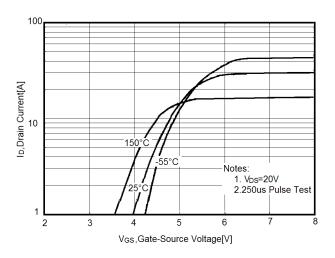


Figure 2. Safe operating area for TO-220F

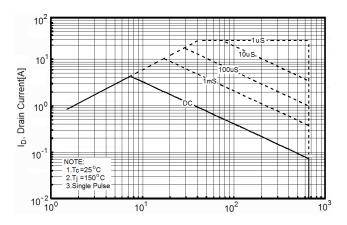


Figure4. Output characteristics

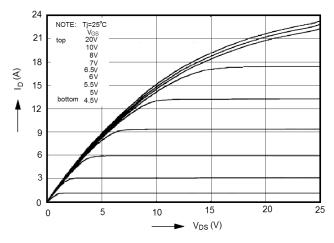


Figure6. Static drain-source on resistance

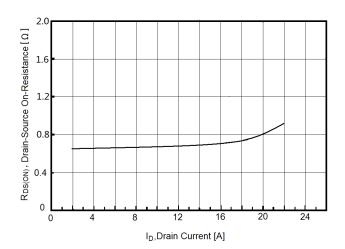
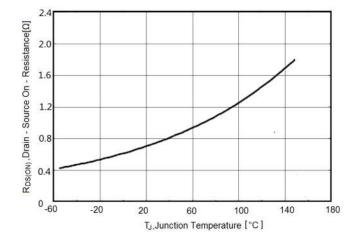




Figure7. R_{DS(ON)} vs Junction Temperature

Figure8. BV_{DSS} vs Junction Temperature



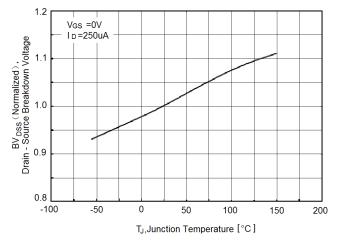


Figure9. Maximum I_D vs Junction Temperature

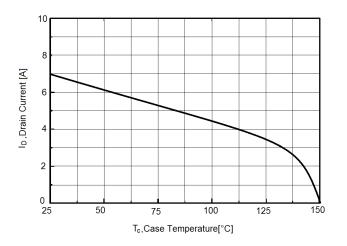


Figure11. Gate charge waveforms



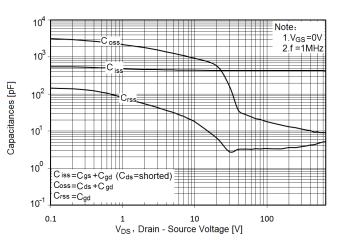
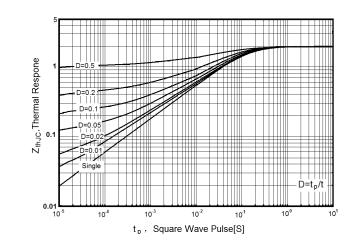
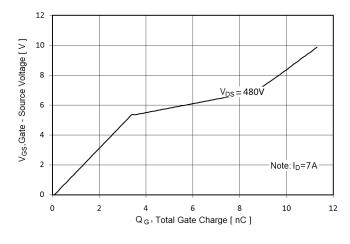


Figure12. Transient Thermal Impedance

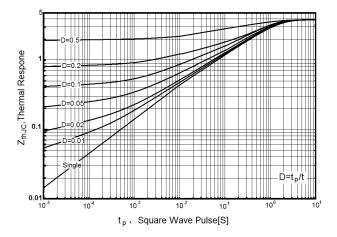




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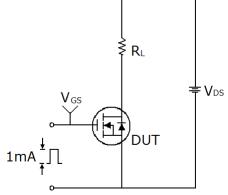
Figure13. Transient Thermal Impedance for TO-220F

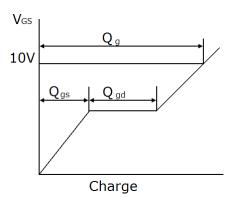




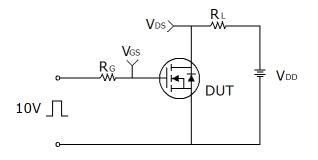
Test circuit

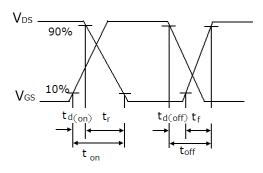
1) Gate charge test circuit & Waveform



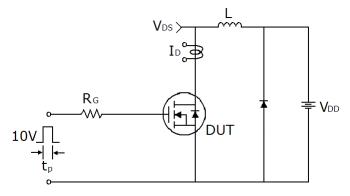


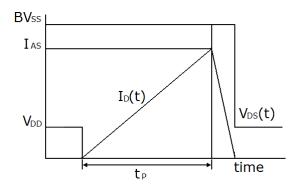
2) Switch Time Test Circuit:





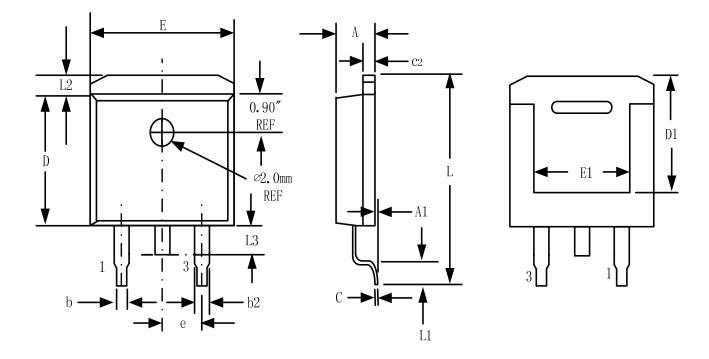
3) Unclamped Inductive Switching Test Circuit & Waveforms







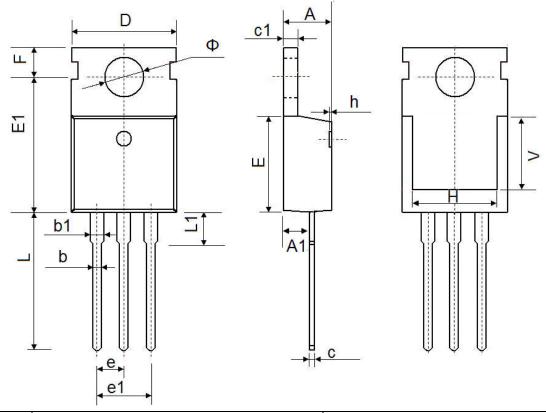
TO-263-3L Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.32	4.57	0.170	0.180	
A1	-	0.25		0.010	
b	0.71	0.94	0.028	0.037	
b2	1.15	1.40	0.045	0.055	
с	0.46	0.61	0.018	0.024	
c2	1.22	1.40	0.048	0.055	
D	8.89	9.40	0.350	0.370	
D1	8.01	8.23	0.315	0.324	
E	10.04	10.28	0.395	0.405	
E1	7.88	8.08	0.310	0.318	
е	2.54	2.54 BSC		BSC	
L	14.73	15.75	0.580	0.620	
L1	2.29	2.79	0.090	0.110	
L2	1.15	1.39	0.045	0.055	
L3	1.27	1.77	0.050	0.070	



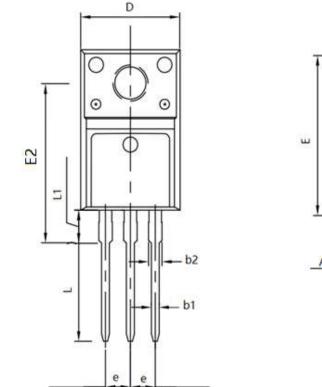
TO-220-3L-C Package Information

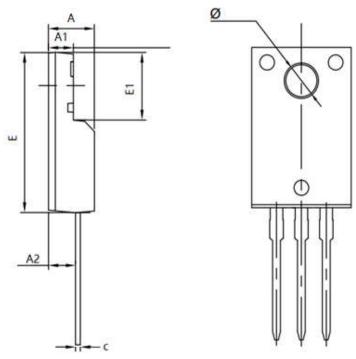


Cumple of	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540 TYP.		0.100	TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500 REF.		0.295 REF.		
Ф	3.400	3.800	0.134	0.150	



TO-220F Package Information





Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	4.500	4.900	0.177	0.193	
A1	2.340	2.740	0.092	0.108	
A2	2.560	2.960	0.101	0.117	
b1	0.700	0.900	0.028	0.035	
b2	1.180	1.580	0.046	0.062	
с	0.400	0.600	0.016	0.024	
D	9.960	10.360	0.392	0.408	
E	15.670	15.970	0.617	0.629	
E1	6.500	6.900	0.256	0.272	
E2	15.500	16.100	0.610	0.634	
е	2.540	2.540 TYP) TYP	
Φ	3.080	3.280	0.121	0.129	
L	12.640	13.240	0.498	0.521	
L1	3.030	3.430	0.119	0.135	



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